

WHAT IS CLAIMED IS:

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1. A photoimageable composition suitable for use as a negative photoresist comprising:
 - (a) about 75% to about 95% by weight of at least one epoxidized polyfunctional bisphenol A formaldehyde novolak resin;
 - (b) about 5% to about 25% by weight of at least one polyol reactive diluent; and
 - (c) at least one photoacid generator in an amount from about 2.5 to about 12.5 parts per hundred parts of resin and reactive diluent, which initiates polymerization upon exposure to near-ultraviolet radiation;
dissolved in a sufficient amount of coating solvent.
2. The composition of claim 1 wherein the at least one epoxidized polyfunctional bisphenol A formaldehyde novolak resin is one epoxy resin having an average of about eight epoxy groups and having an average molecular weight of about 1400 gram/mole and having an epoxy equivalent weight of about 215 gram/mole.
3. The composition of claim 1 wherein the photoacid generator is a triaryl sulfonium hexafluoroantimonate salt.
4. The composition of claim 1 wherein the at least one polyol reactive diluent is either a difunctional or trifunctional polycaprolactone polyol reactive diluent.

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